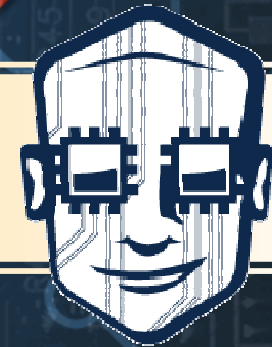


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SANTA CLARA CONVENTION CENTER



DDR Memory Channel Design from Passive Stub Equalizer Perspective

Jongbae Park, Myunghyun Ha, Qin Li
Intel Corporation



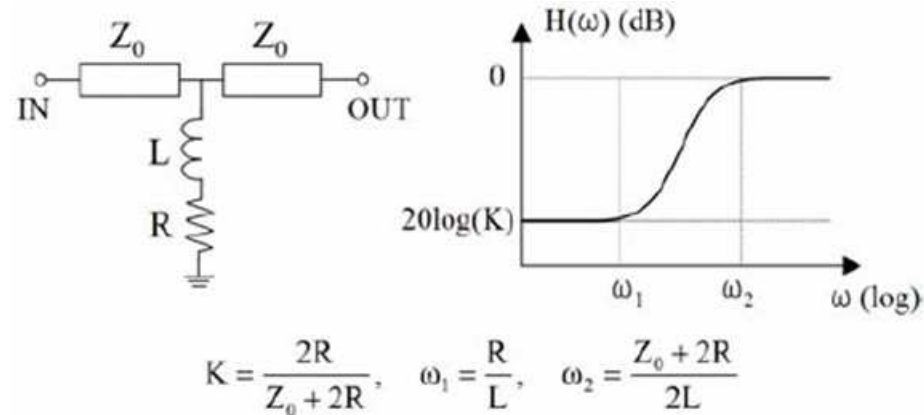
Agenda

1. Introduction
2. Passive Stub Equalizer
 - Basic Principles of Passive Stub Equalizer
 - Control of Passive Stub Equalizer
 - Demonstration of Passive Stub Equalizer through Simulation and Measurement
3. Application of EQ Design Concept to Memory Channel
 - LPDDR3 CA Channel
 - DDR4 DQ Channel
4. Summary

Motivation

- ✓ Both data rates and density of memory are getting faster and higher, respectively, driven by process technology and consumer demand.
 - ✓ Suffering higher inter-symbol interference in multi-drop memory channel.
 - ✓ Design of memory channel becomes more challenging.
- ➔ Will introduce the design concept of multi-rank memory channel from passive stub equalizer perspective.

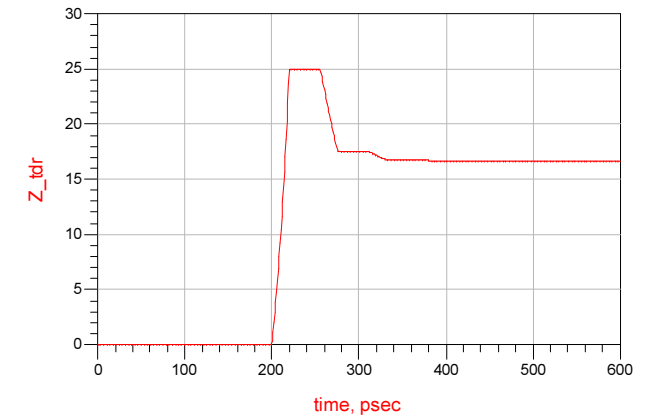
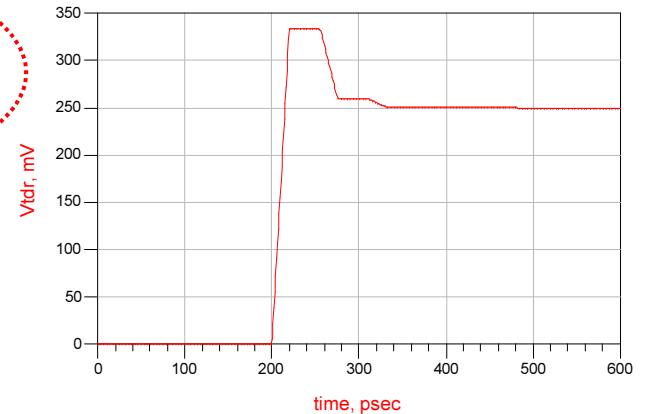
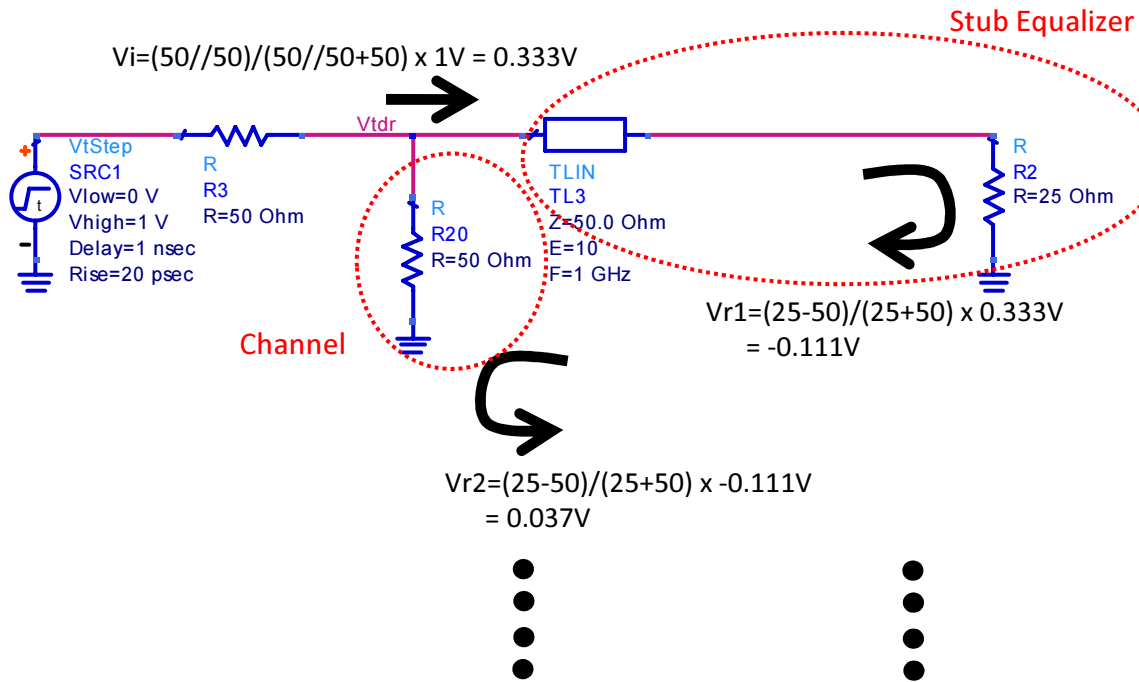
Representative Schematic of Passive Equalizer



- Inductor determines the high frequency gain.
- Resistor determines the DC de-emphasis level.
- There are many publications which discuss about how to implement the inductor “L”. For example, using an inductive via or trace with ground cut.
- What about Regular 50~60ohm Transmission line for the inductor implementation??

Passive Stub Equalizer

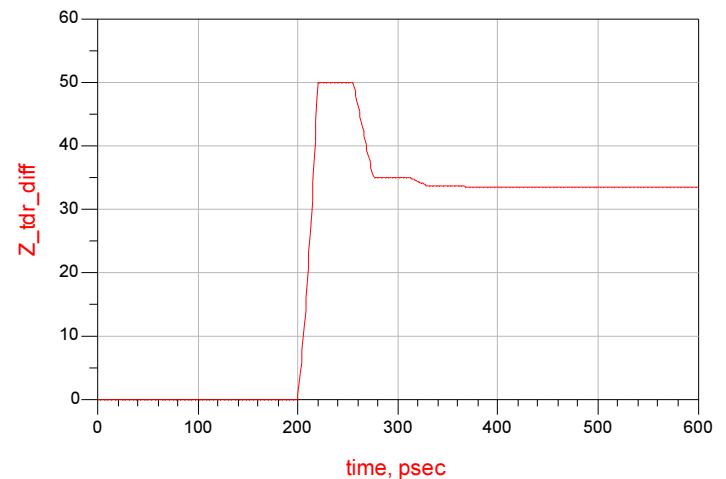
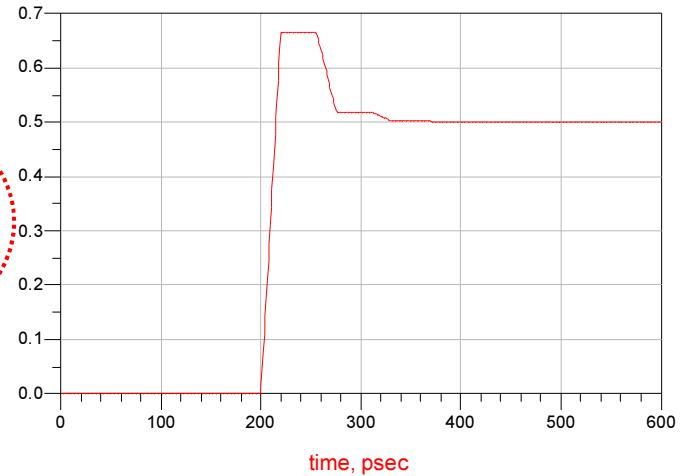
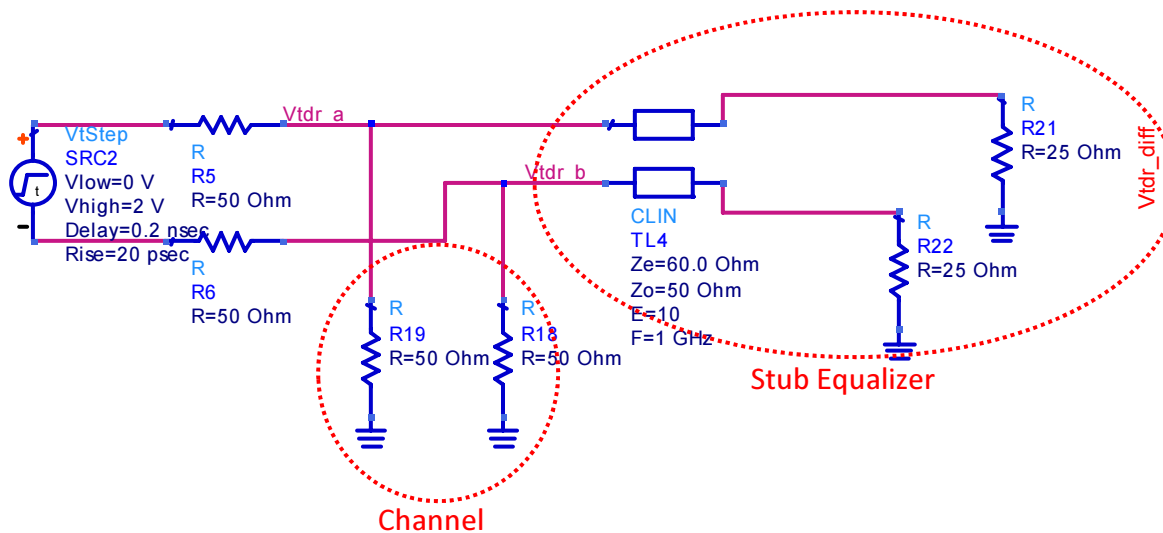
[Single-ended Signaling]



- * Typical high impedance trace also can be used to implement the inductor.
- * De-emphasis is controlled by stub's Z0/TD and its termination.

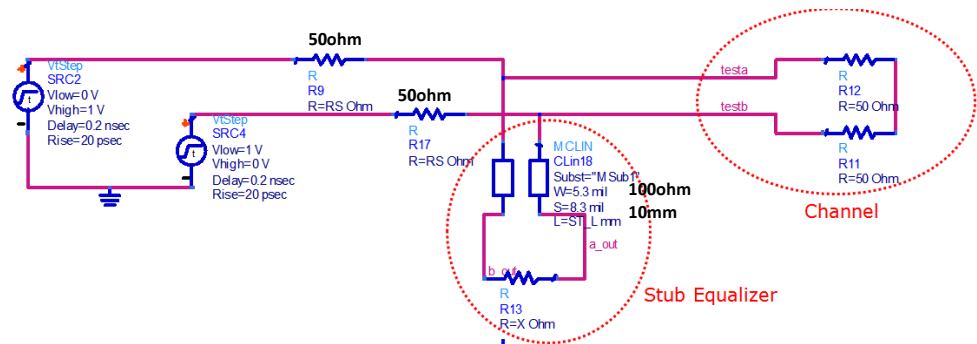
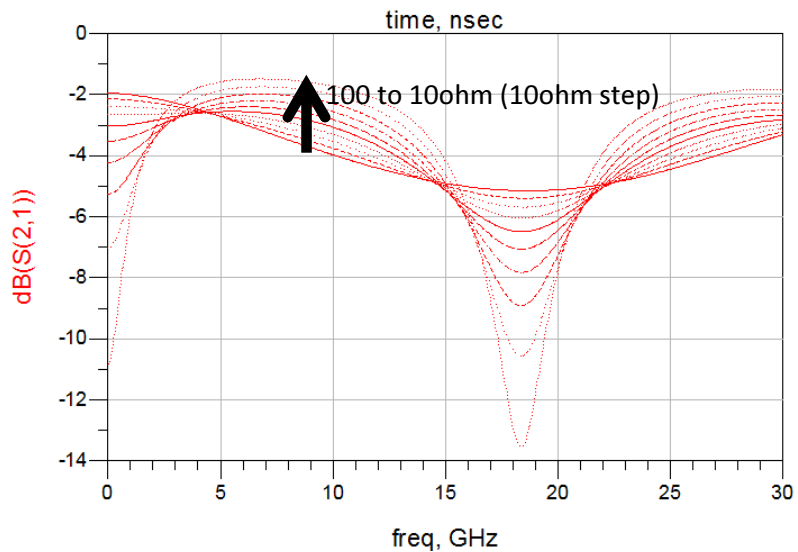
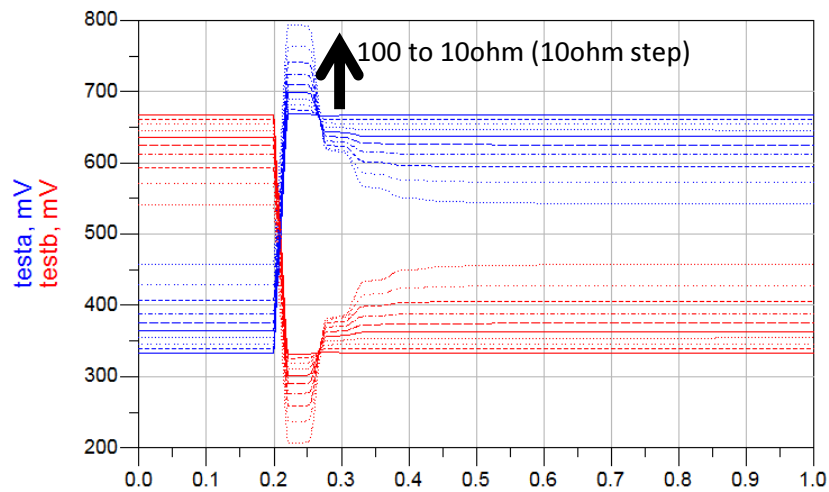
Passive Stub Equalizer

[Differential Signaling]



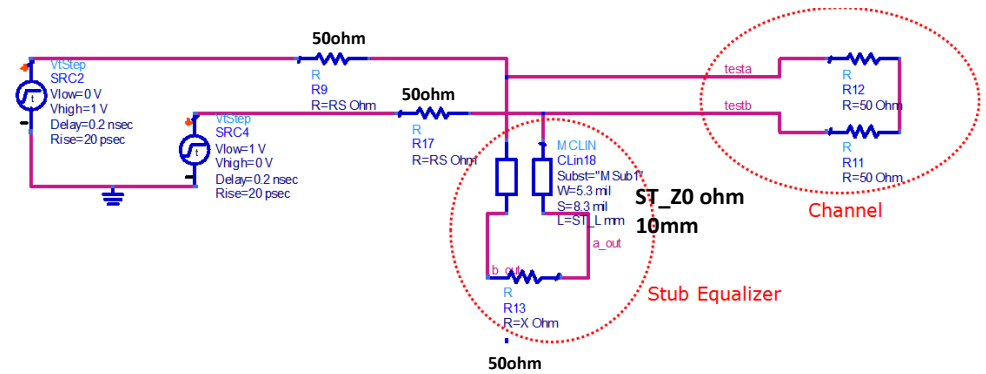
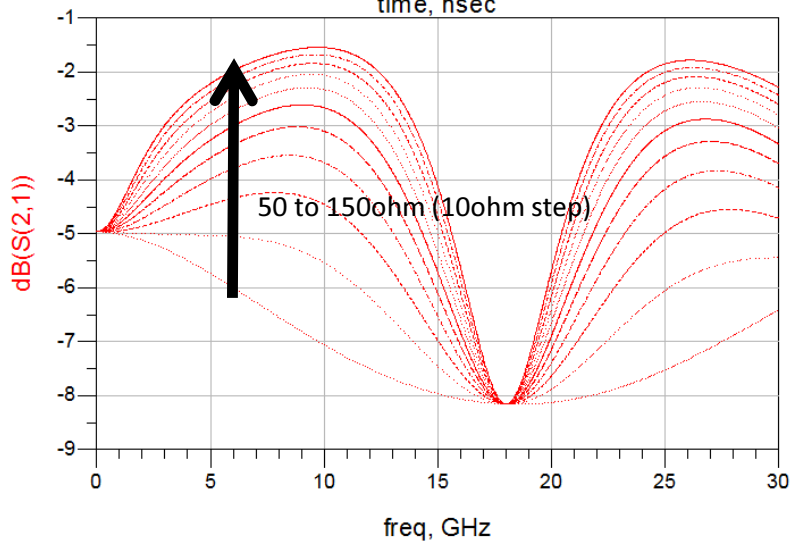
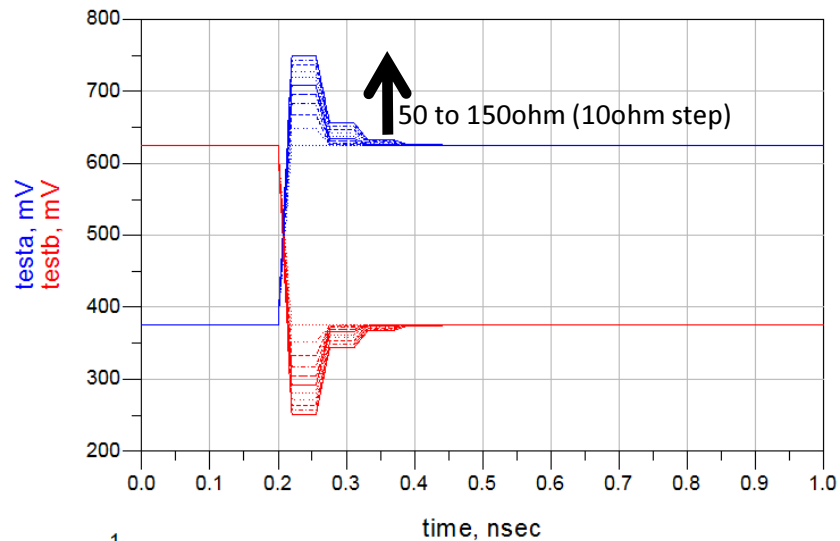
- * Stub passive equalizer is also applicable to differential channel.
- * De-emphasis is controlled by stub's differential Z_0/TD and its differential termination.
- * To get high impedance stub transmission line, a loosely coupled traces are recommended.

Stub Termination Impacts



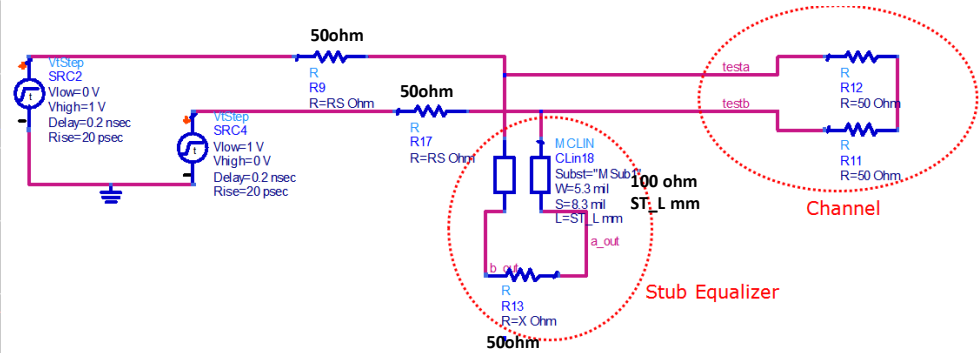
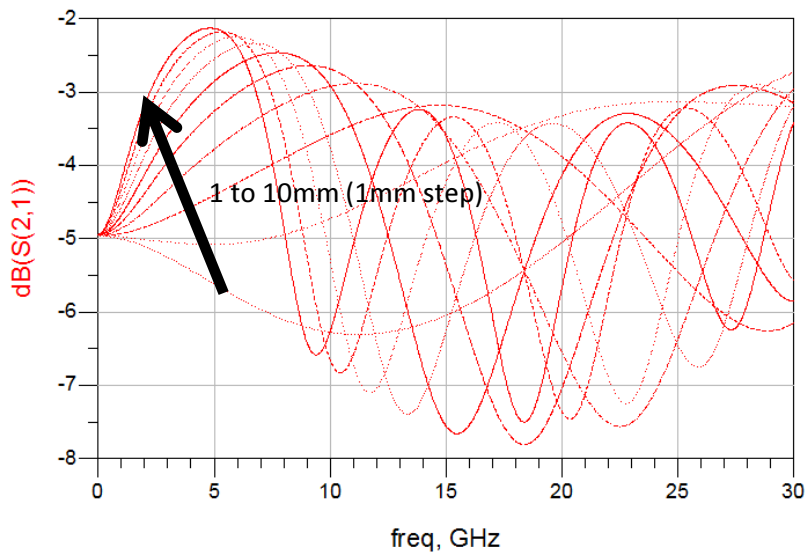
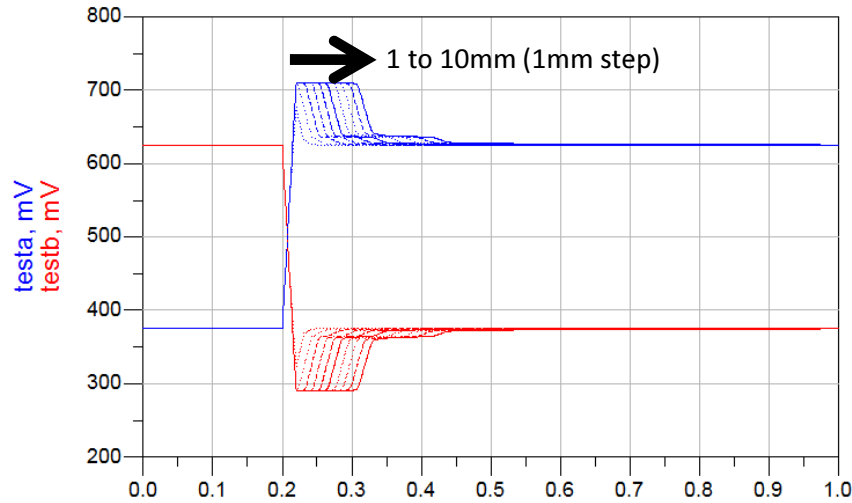
* Stub-termination has to be smaller than the stub trace's characteristic impedance to be an equalizer.

Stub Trace Impedance Impacts



* Higher stub trace impedance will provide higher ac gain.

Stub Trace Length Impacts



- * AC gain is increased as the stub trace length increases.
- * However, stub trace length also limits and determines the operating frequency range of the stub equalizer.

Stack-up of Fabricated DUT for Demonstration

		Target (Mil)	Measured Thickness (Mil)	Dk/Df @ 2GHz
	S/M	0.5	0.59	Dk=3.90 Df=0.027
	Cu Plating	1.9	2.53	
1	SIG	0.7		
	Dielectric	2.9	2.68	Dk=3.86 Df=0.024
2	GND	1.2	1.2	
	Dielectric	66	67.1	
3	GND	1.2	1.2	
	Dielectric	2.9	2.9	Dk=3.86 Df=0.024
4	SIG	0.7	2.47	
	Cu Plating	1.9		
	S/M	0.5	0.58	Dk=3.90 Df=0.027

[DUT Stack-up]

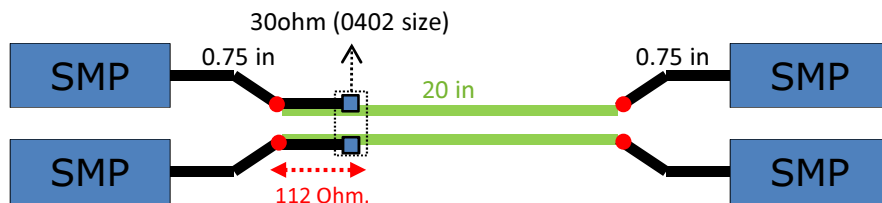
Patterns in Fabricated DUT for Demonstration



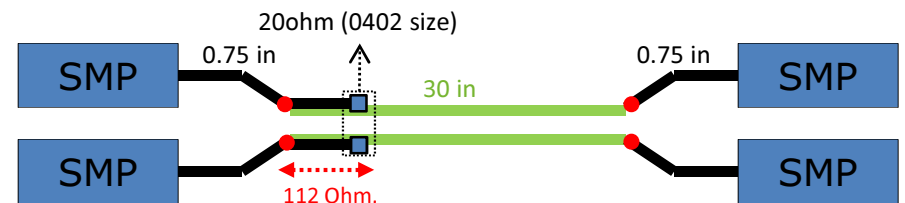
[100ohms, 21.5inch-long Differential Trace]



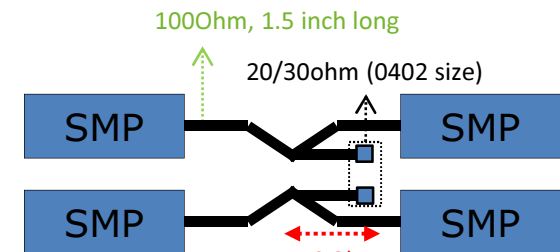
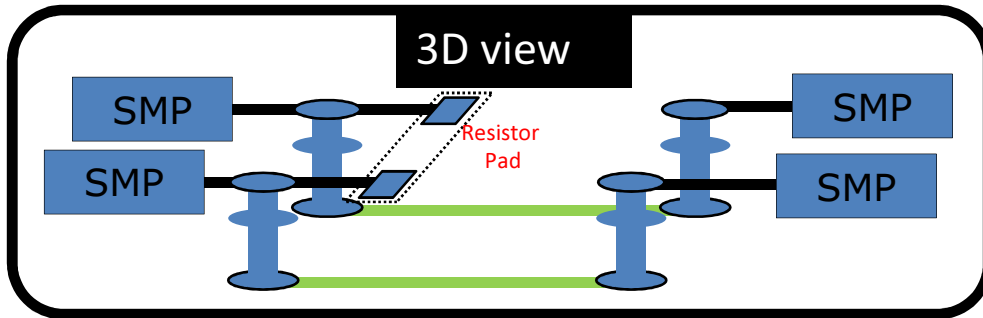
[100ohms, 31.5inch-long Differential Trace]



[100ohms, 21.5inch-long Differential Trace with EQ]

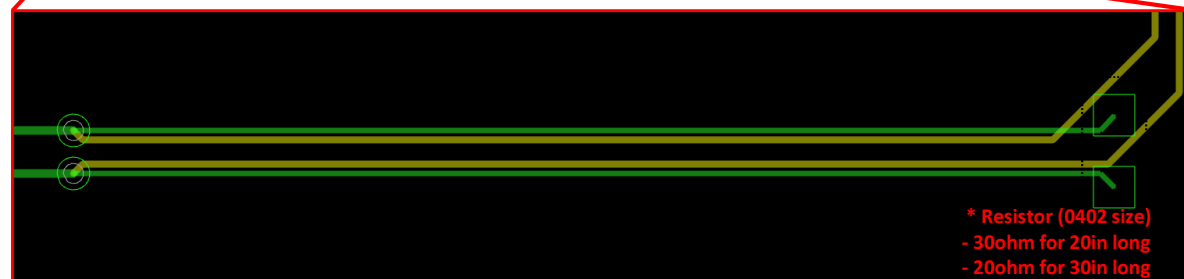
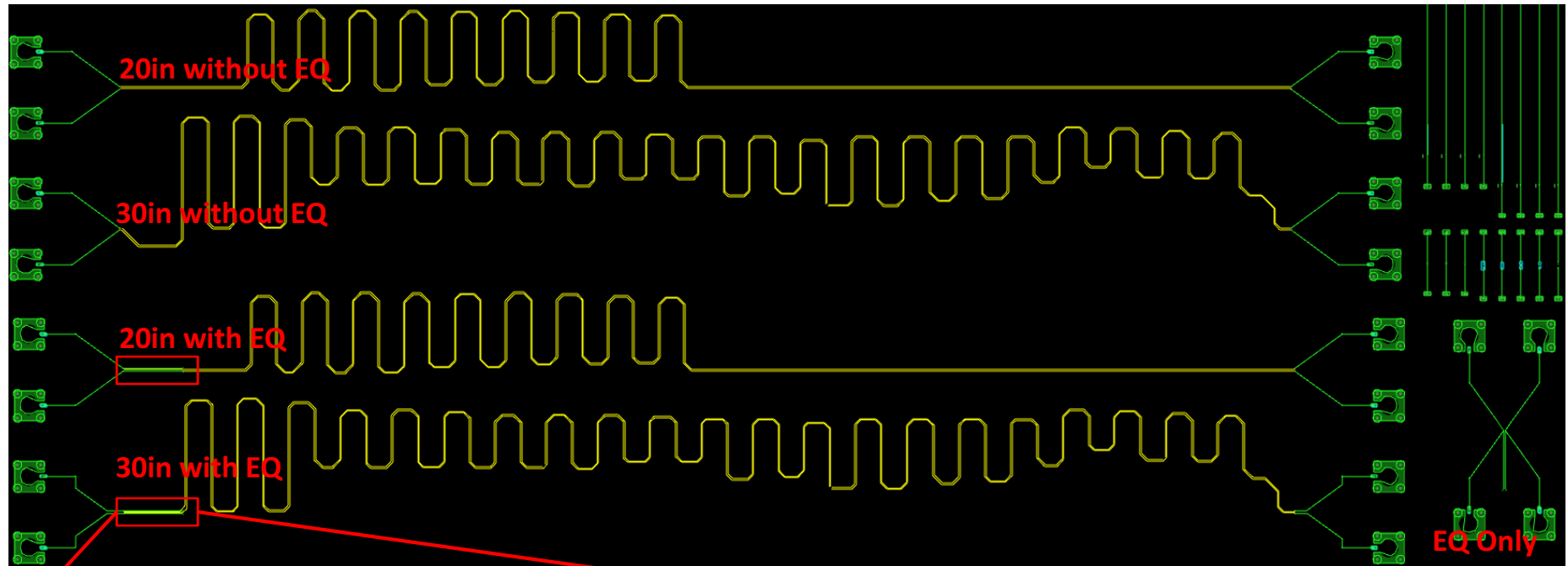


[100ohms, 31.5inch-long Differential Trace with EQ]

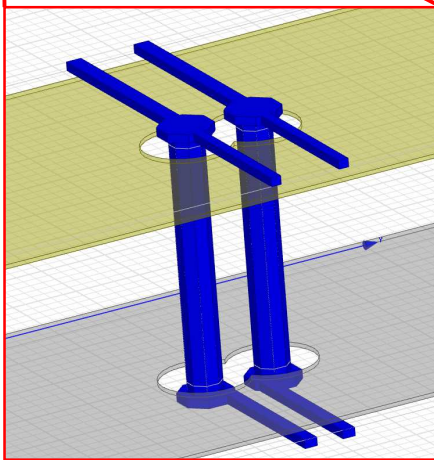
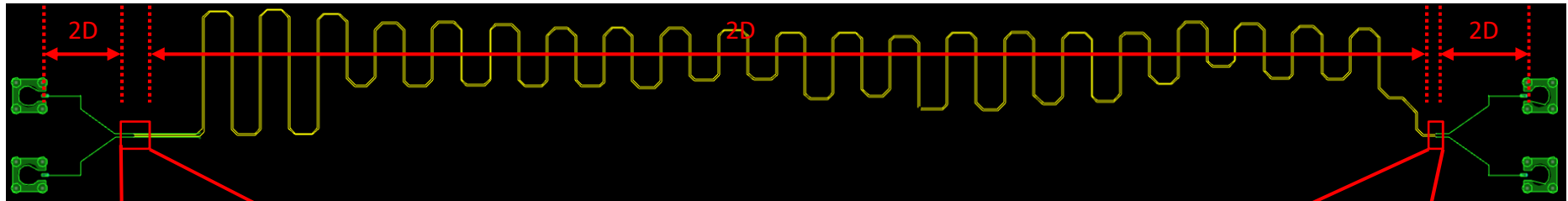


[100ohms, 1.5inch-long Differential Trace with EQ]

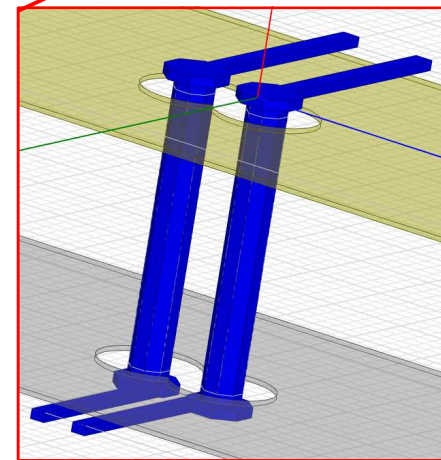
Layout of DUT



Modeling of DUT

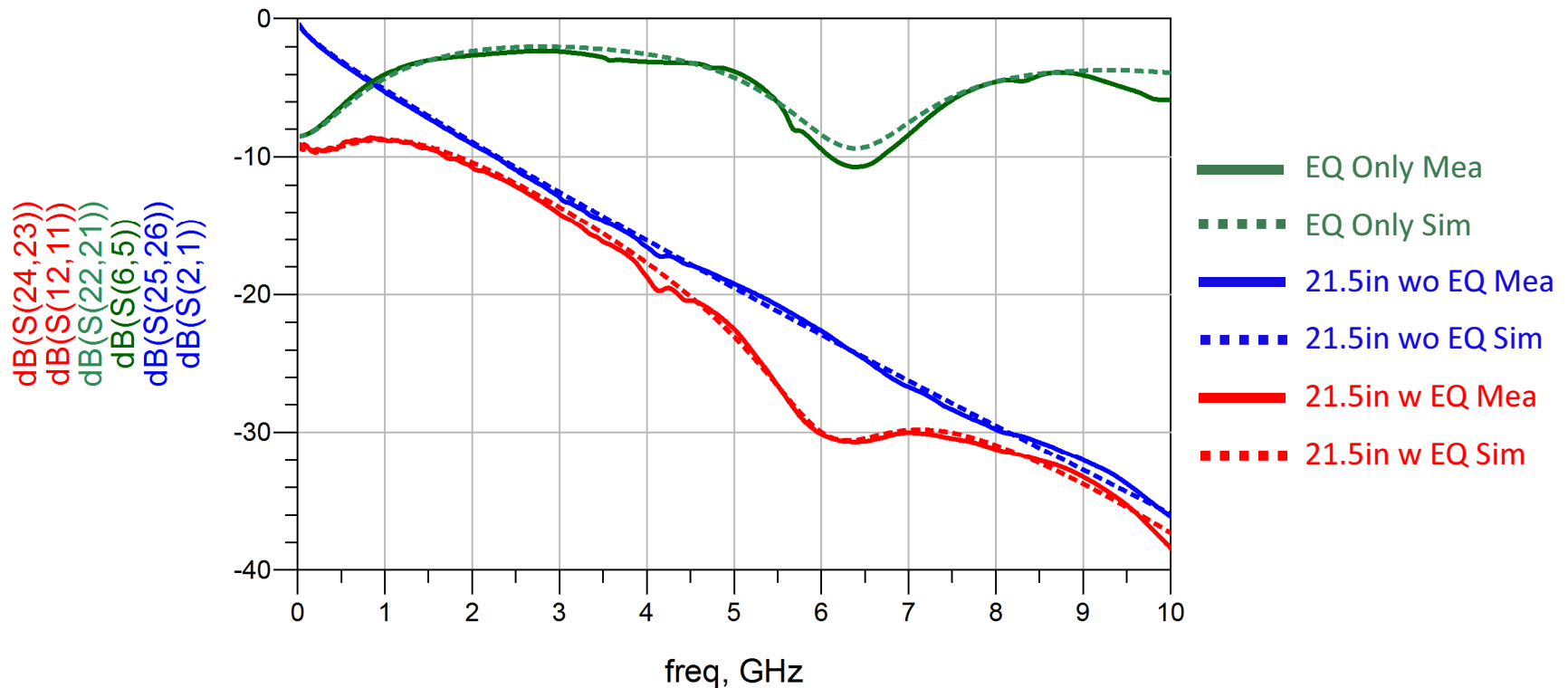


[Model in HFSS]



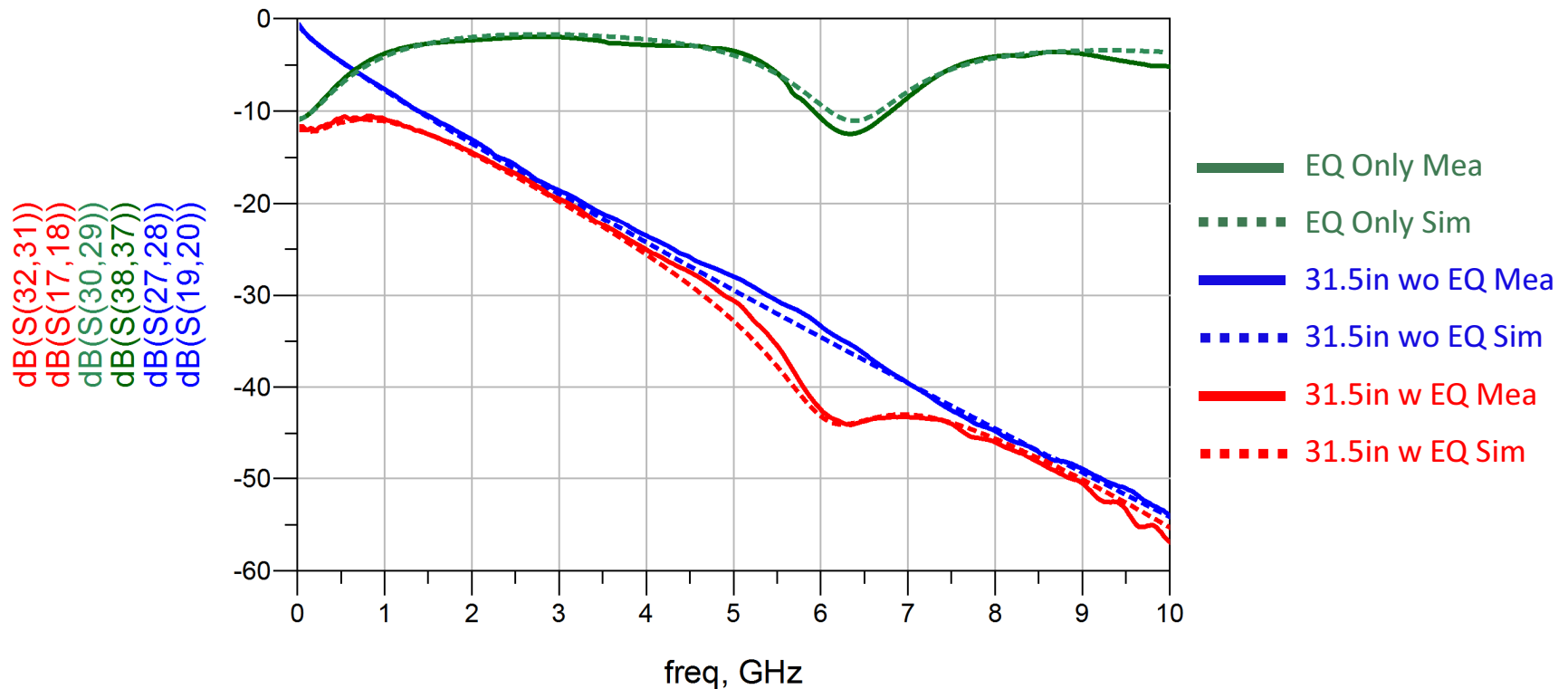
[Model in HFSS]

Correlation [21.5inch Trace]



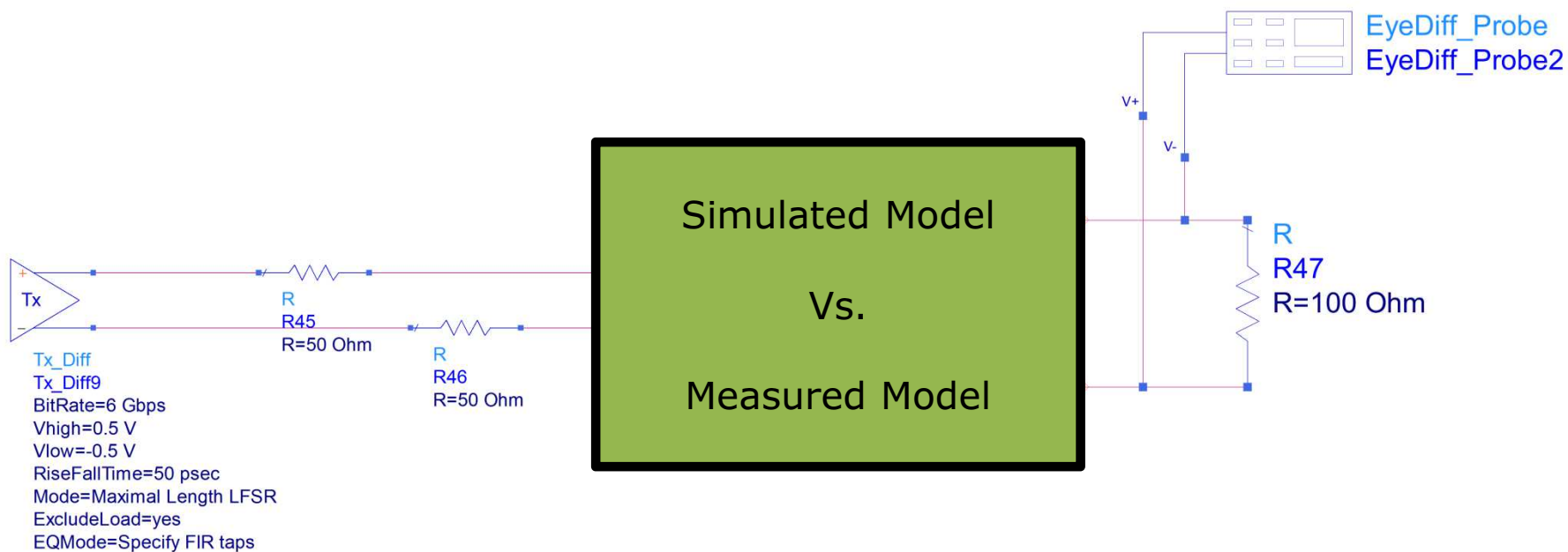
* Simulated insertion losses are correlated very well with the measured one.

Correlation [31.5inch Trace]



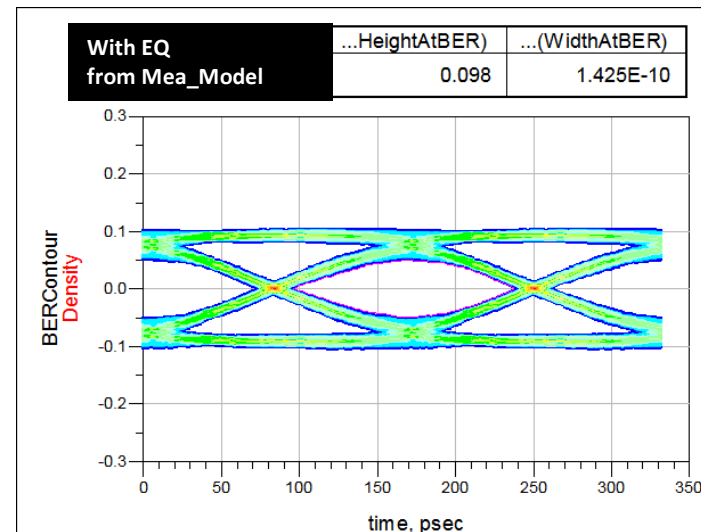
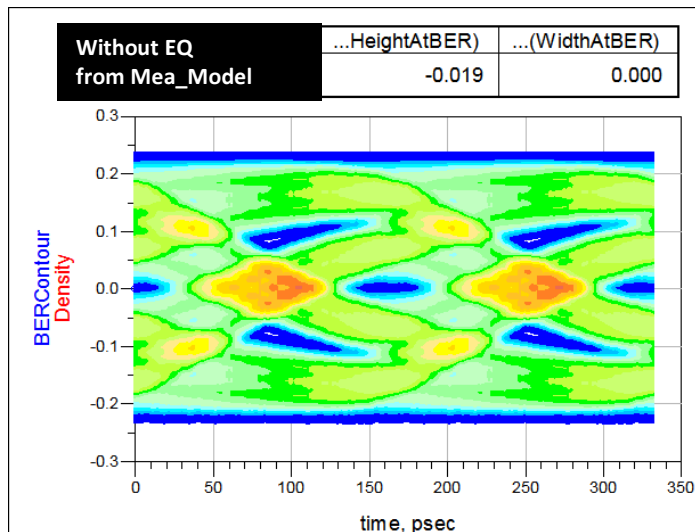
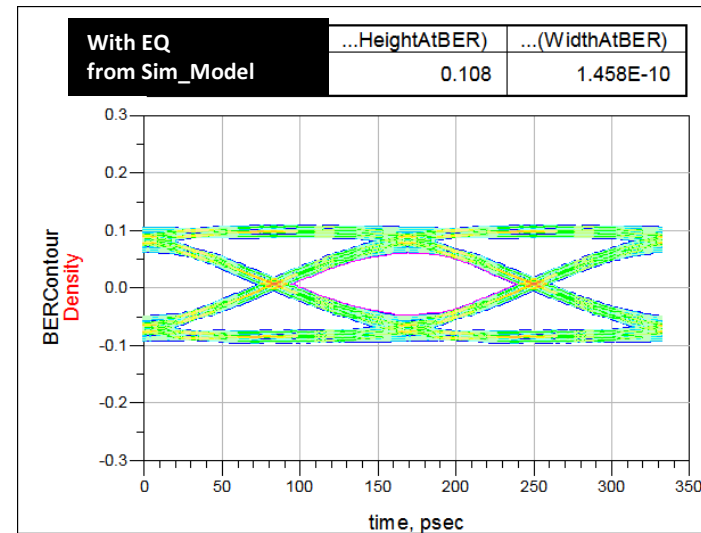
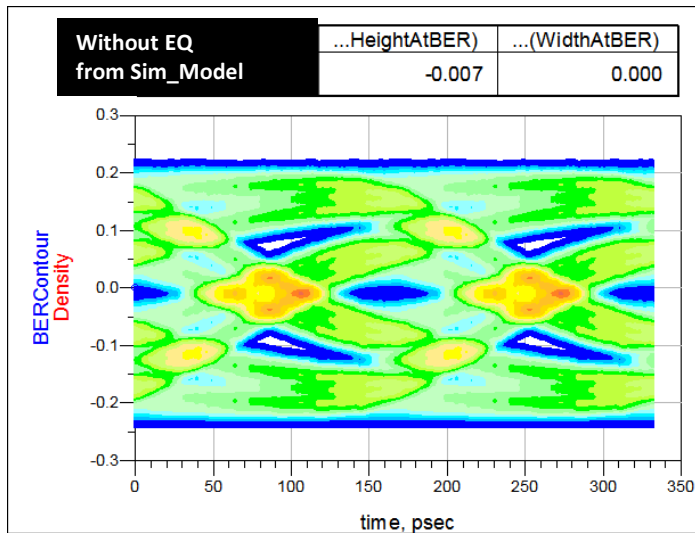
* Simulated insertion losses are correlated very well with the measured one.

Time-Domain Correlation for 6Gbps Signaling

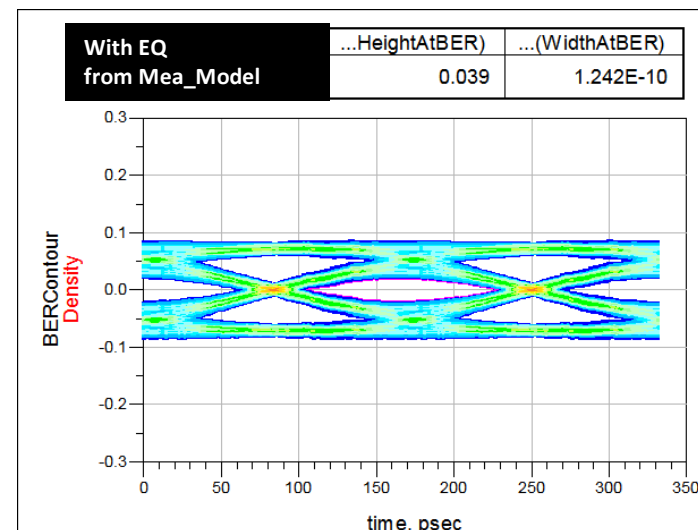
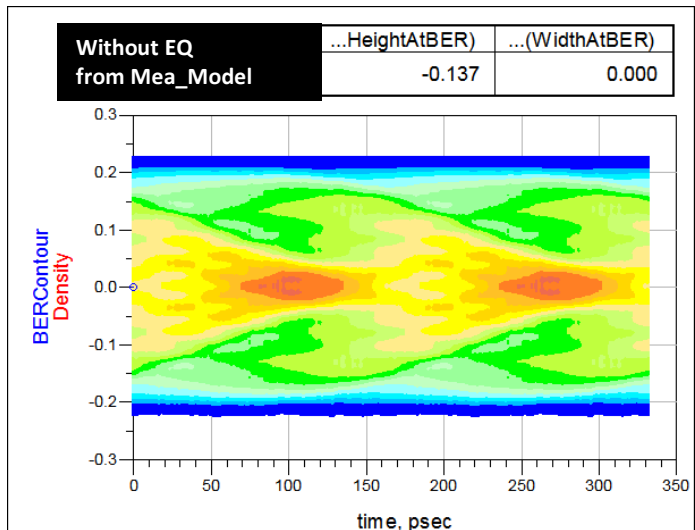
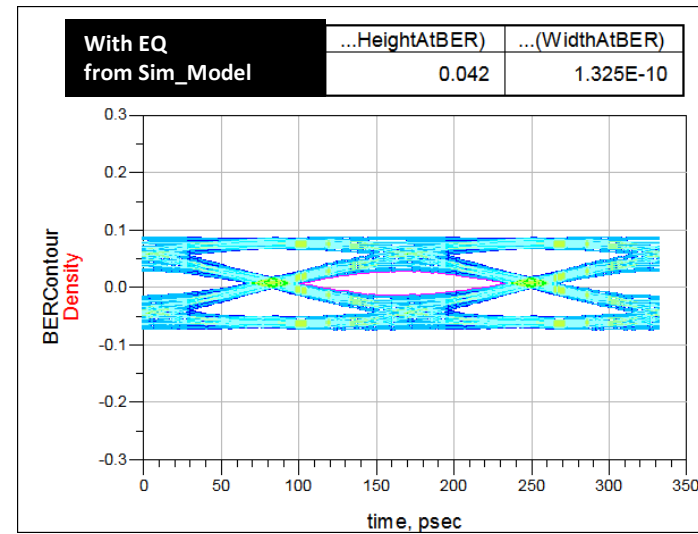
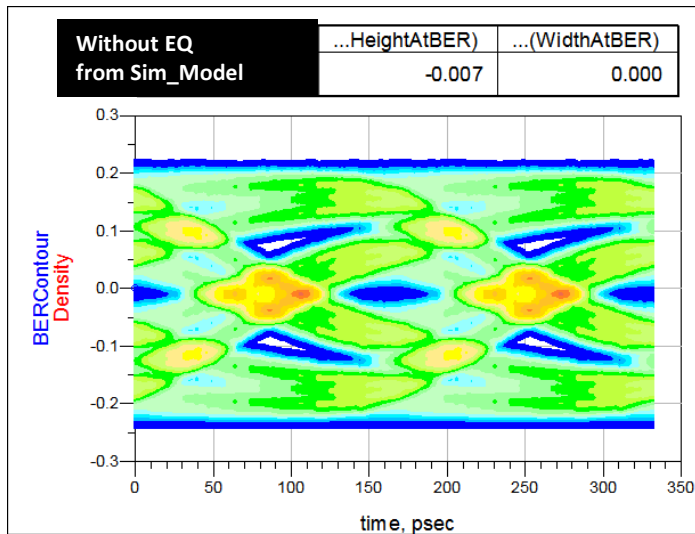


* The frequency-domain models from simulations and measurements were used for the 6 Gbps time-domain simulation.

Correlation [21.5inch Trace]



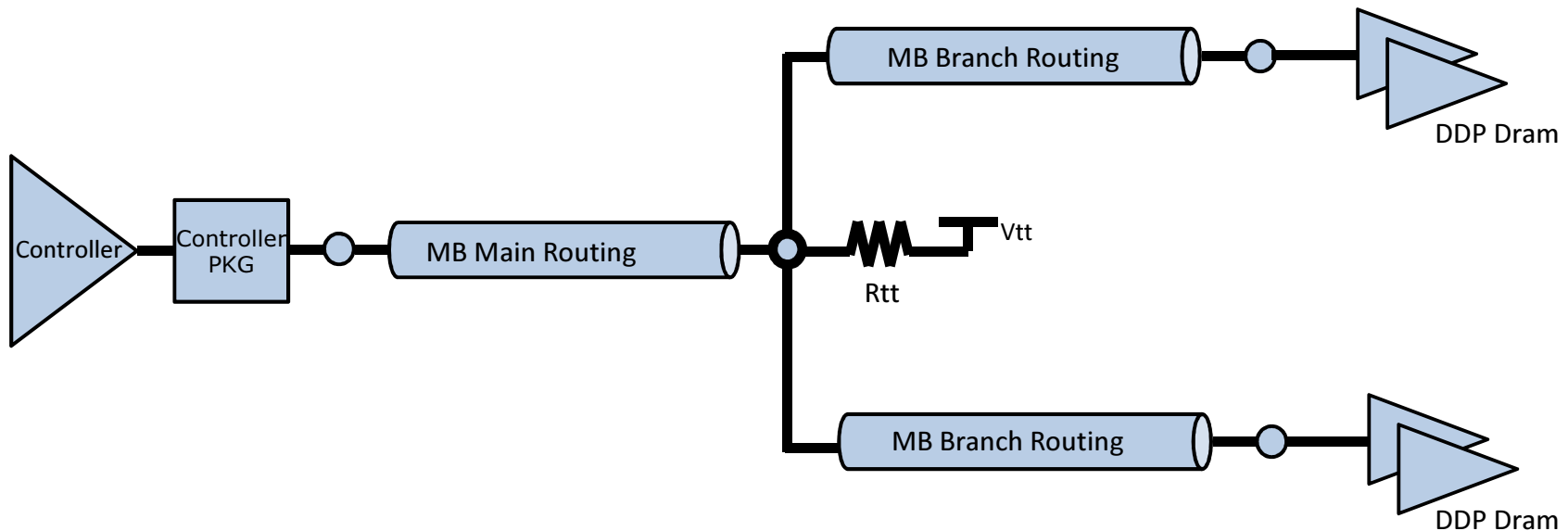
Correlation [31.5inch Trace]



Agenda

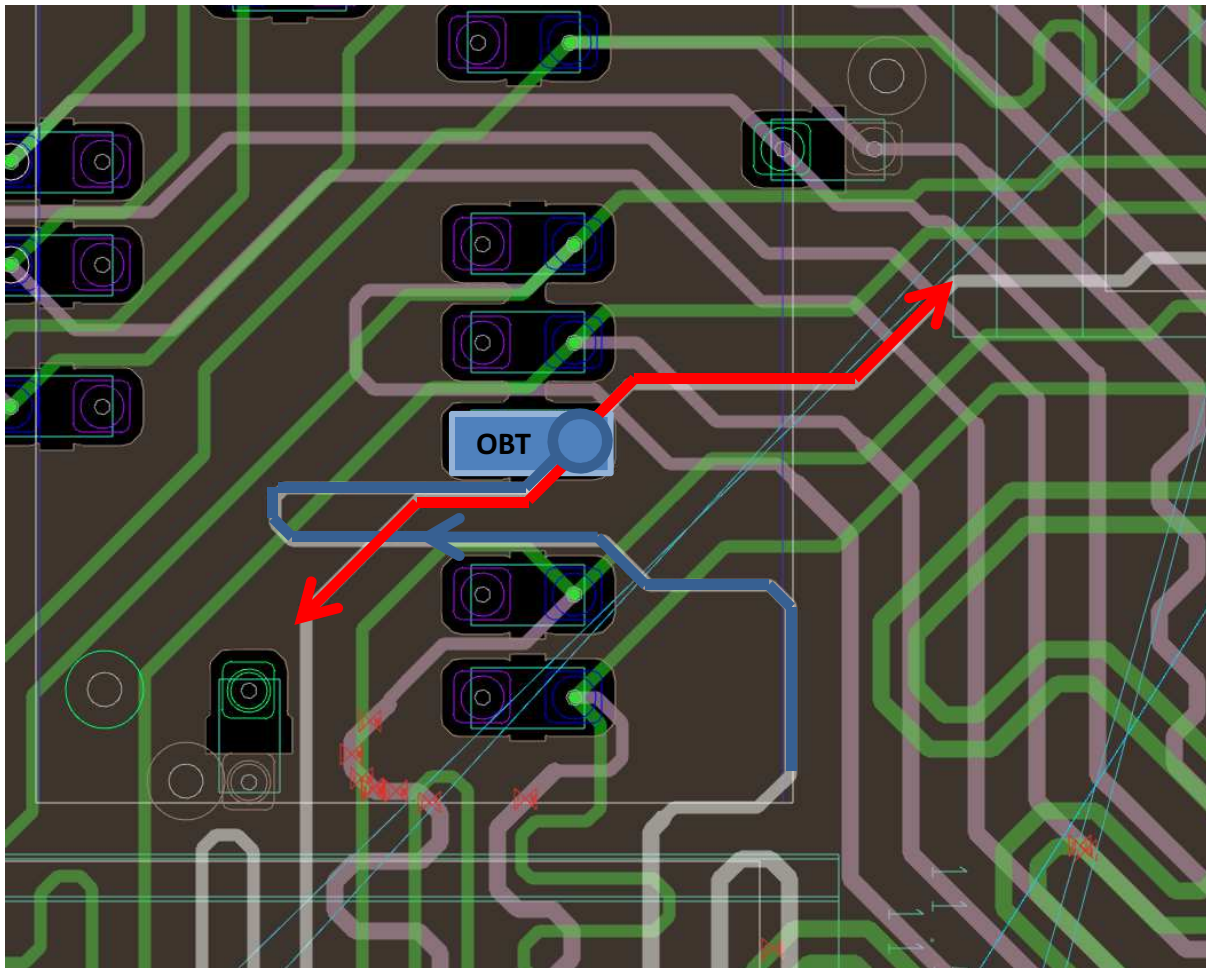
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 - [On-die Termination] DDR4 DQ Channel
4. Summary

Typical LPDDR3 CA Channel



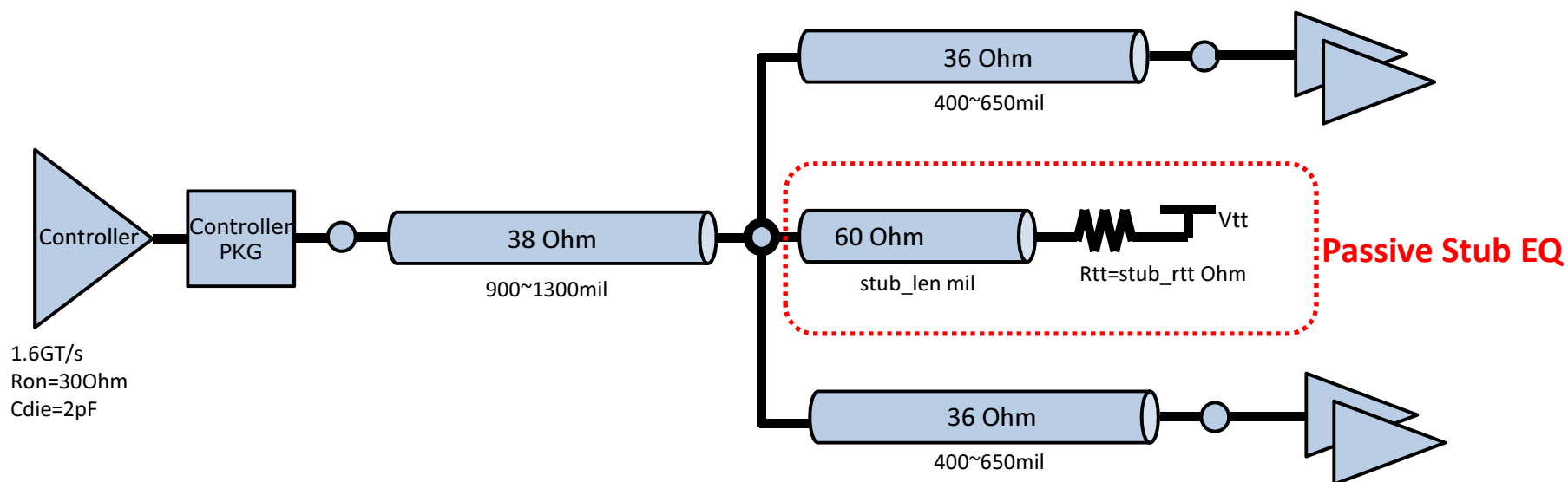
- LPDDR3 CA channel uses on-board termination, instead of on-die termination.
- In many practical CA layouts, the impedance of MB main routings are not much lower than that of branch routings, due to the routing constraints and complexity.
- Huge impedance mismatch at the junction cause a huge ISI.

Layout Example of On-board Termination



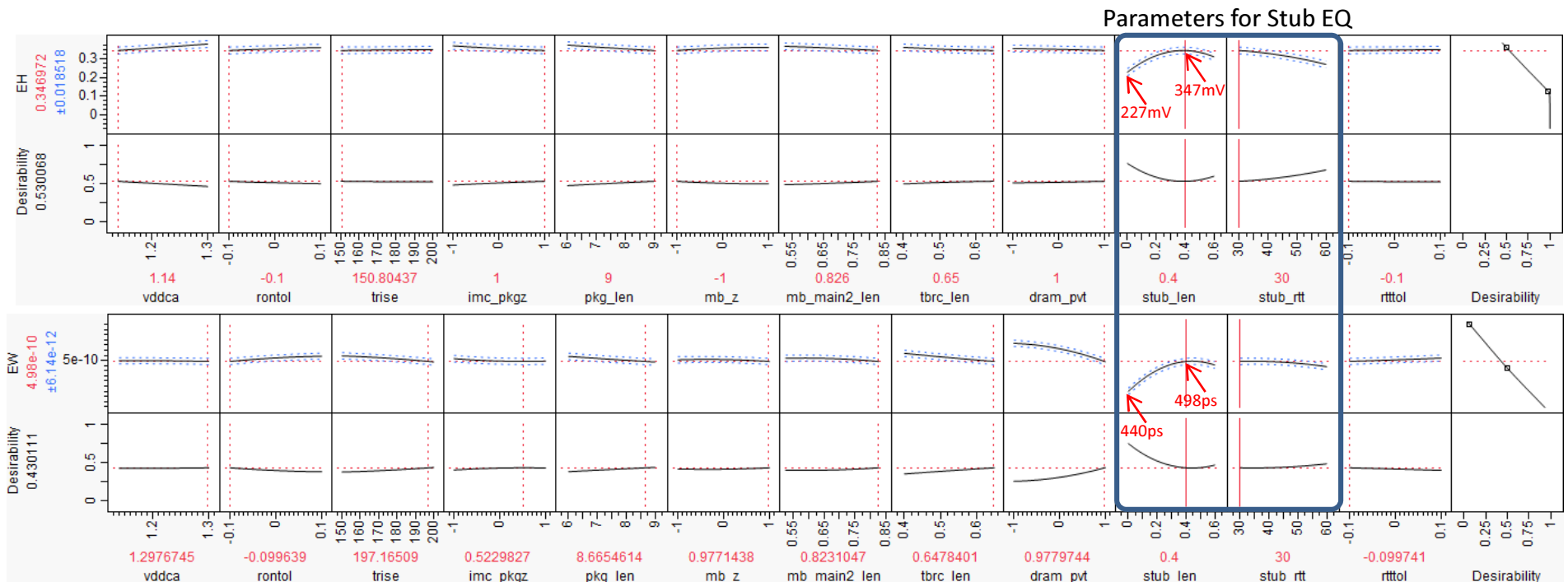
- OBT is directly connected at the location of the junction for all CA signals.

LPDDR3 CA Channel with Stub Equalizer



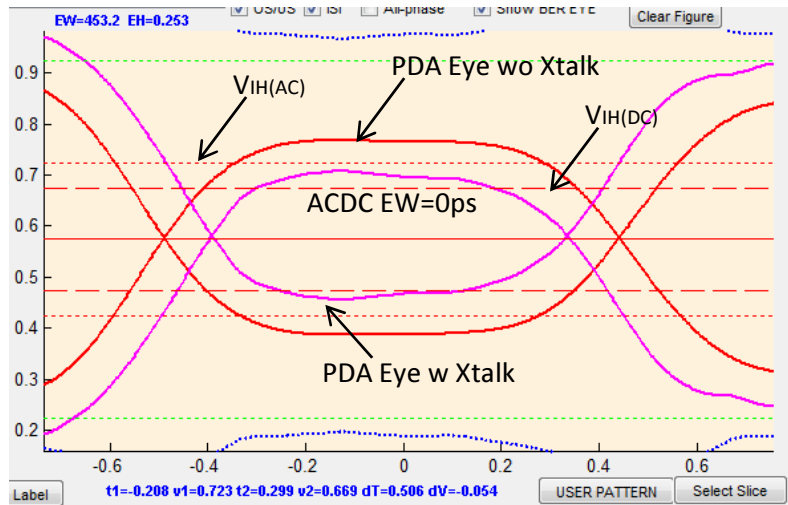
- A 60 ohms transmission line is inserted between the branch junction and the OBT. The combination of the inserted transmission line and the OBT becomes a **passive stub equalizer** for the CA channel.
- The implemented stub equalizer will enhance the signal quality by equalizing the high frequency ISI caused by the impedance discontinuity.
- CA channel above was simulated and analyzed to see the sensitivity of each design parameter, by performing DOE simulations at the speed of 1600MT/s.

Sensitivity of each DOE parameter

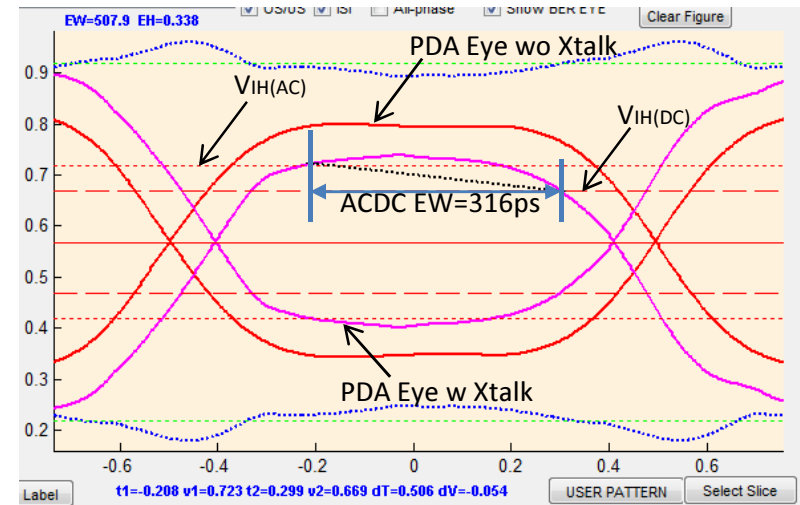


- Five parallel DQ Signals were considered to take into account for the crosstalk impacts.
- Observed the sensitivity of each parameter
 - ✓ Supply Voltage Tolerance
 - ✓ Source Termination Tolerance
 - ✓ Driver Strength
 - ✓ Controller Package Length
 - ✓ Controller Package Impedance Tolerance
 - ✓ Main Routing Length
 - ✓ Branch Length
 - ✓ MB Impedance Tolerance
 - ✓ Dram Package Impedance Tolerance
 - ✓ Stub Transmission Line Length
 - ✓ Stub Termination
- EH and EW were improved by 120 mV/58 ps, respectively, when using the equalizer

Eye Diagrams with/without Stub trace



[0mil Stub with 30ohm Rtt]



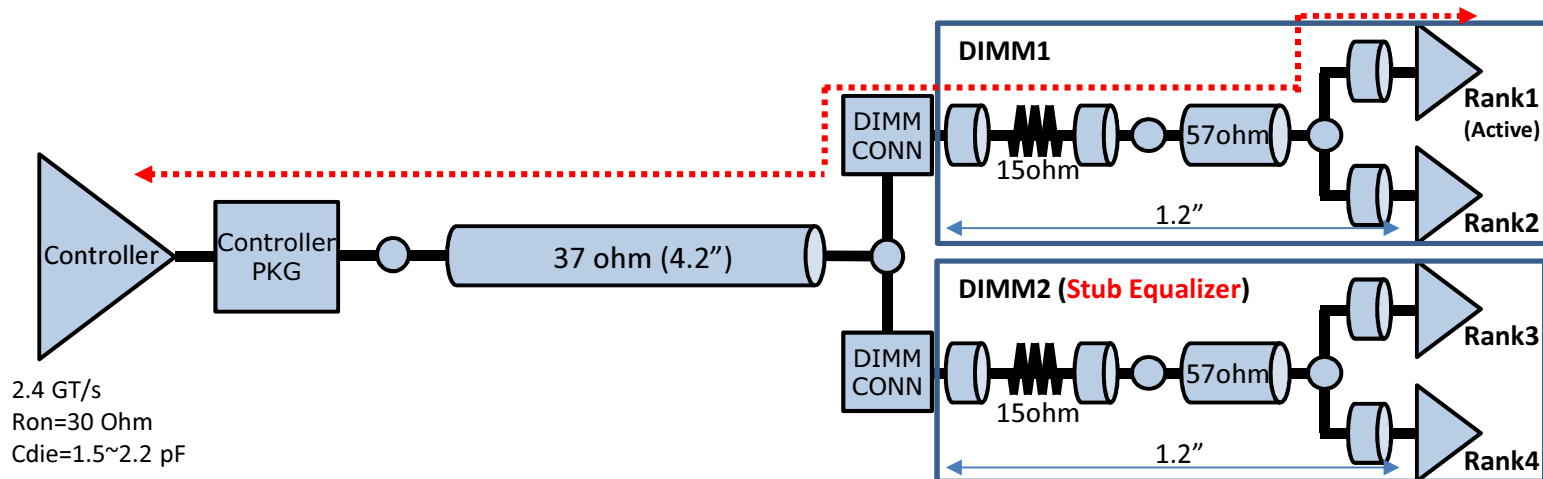
[400mil Stub with 30ohm Rtt]

- When there is no crosstalk, the EH/EW of the worst case PDA eye diagram was improved from 380mV/575ps to 460mV/620ps, by having the 400 mil stub transmission line.
- Even after considering the crosstalk from 4 aggressors, the worst case eye is still improved by the amount of when there is no crosstalk.
- The channel without stub transmission line had “0ps” of ACDC EW (VIH(AC) to VIH(DC)), while 400 mil stub transmission line introduced “316ps” of ACDC EW, which met the LPDDR3 CA specification (175 ps) with an enough margin.

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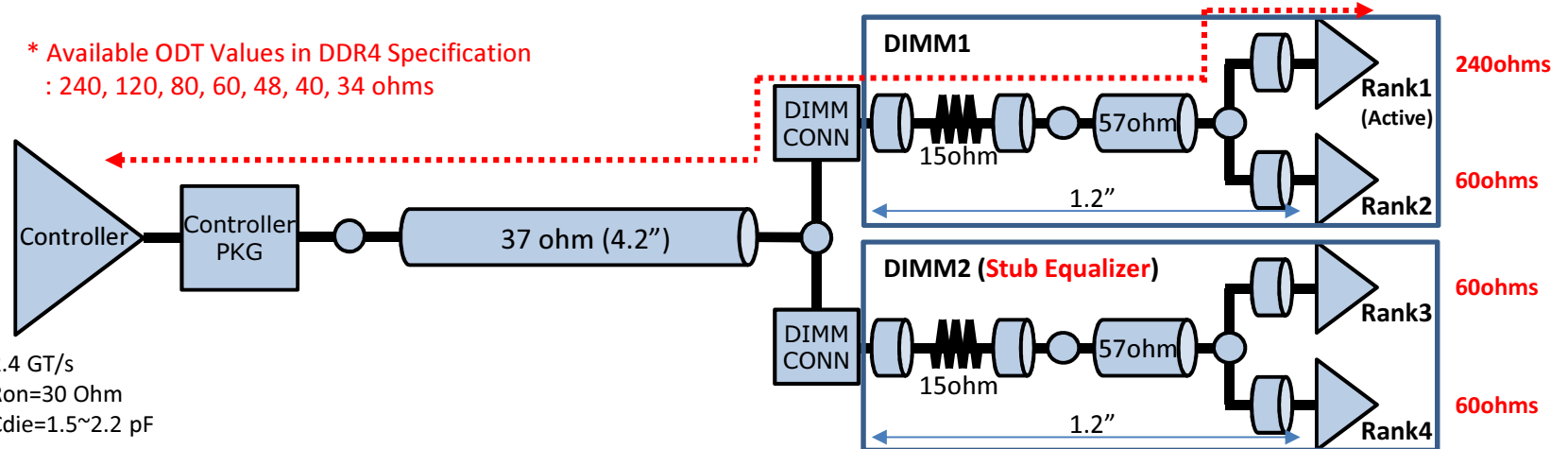
DDR4 2DPC - Tee Topology



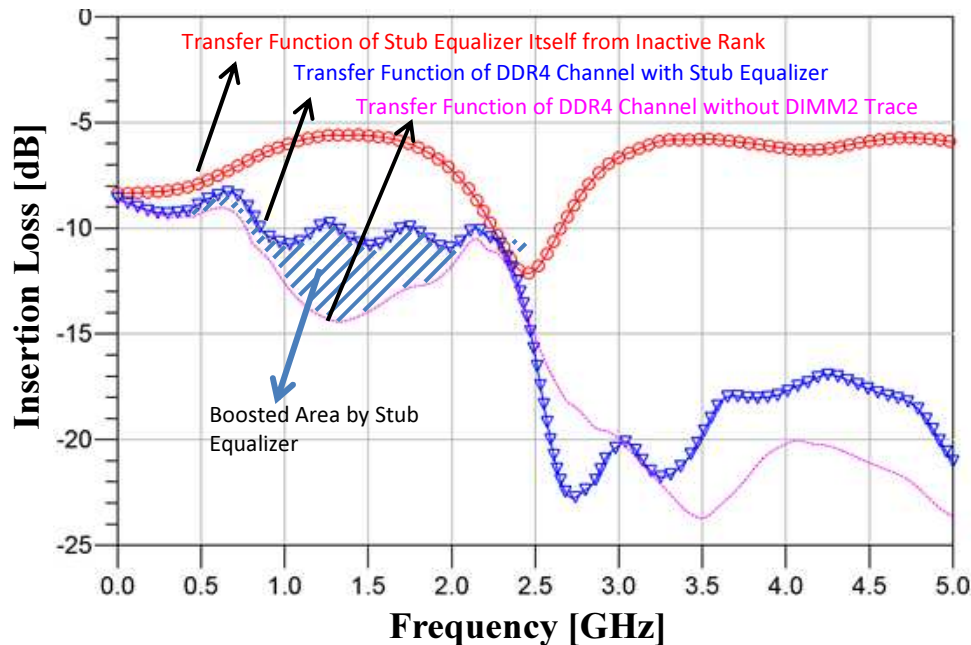
- When writing a bit to the first rank (Rank1; active rank), the channel connected to the rank 3 and rank 4 (inactive ranks) from the junction at via becomes a long stub to the channel (from the controller to the active rank).
- Utilize the inevitable long stub from the inactive ranks (rank 3 and rank 4) as a passive stub equalizer described in the previous chapter.
- To use the inactive rank's stub as a passive stub equalizer, we need to carefully optimize the DIMM2 trace and ODT values. However, DIMM design is not controllable.
- Therefore, ODT values are the only parameters we can optimize, assuming the MB trace impedance and lengths are fixed.

DDR4 2DPC - Tee Topology

* Available ODT Values in DDR4 Specification
: 240, 120, 80, 60, 48, 40, 34 ohms

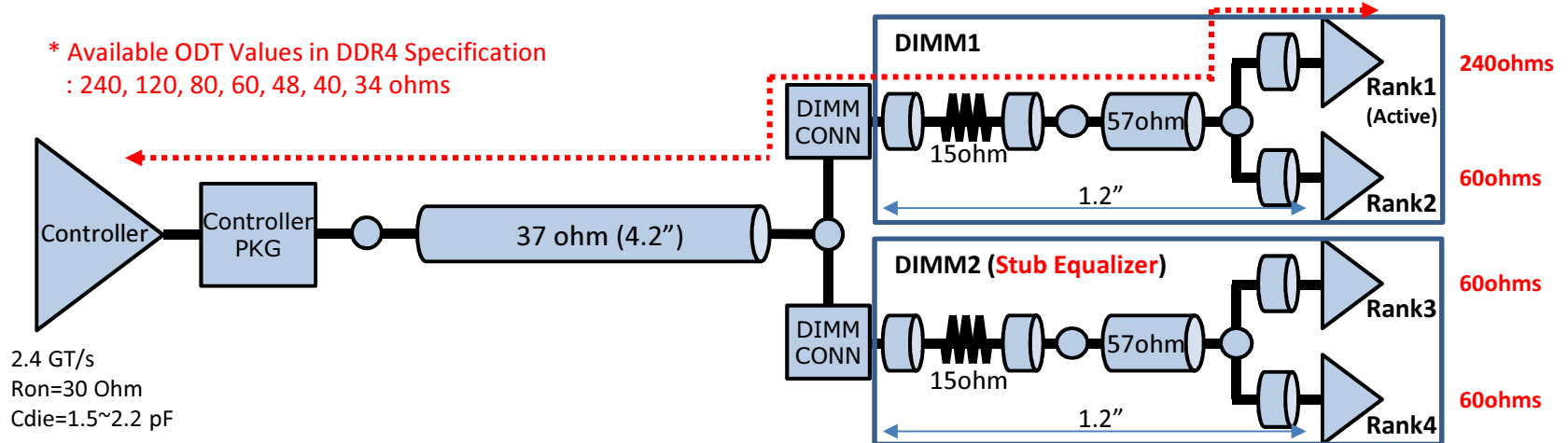


2.4 GT/s
Ron=30 Ohm
Cdie=1.5~2.2 pF



- According to the passive stub equalizer theory, higher characteristic impedance of trace and lower stub termination value increase the ac-gain and the de-emphasis level, respectively.
- Also, the stub termination (ODT) needs to be lower than the stub transmission line, which is mostly set to 55 ~ 60 ohms.
- Lowered the stub termination (ODT) value to 30 ohms (parallel of two 60 ohms ODTs).
- 60 ohms ODT was used for Rank2 to avoid the open stub impact, and 240ohms ODT for Rank1 to have enough DC swing level at Dram.

DDR4 2DPC - Tee Topology



ODT Matrix for 2DPC DQ Tee Topology Channel @ 2133MT/s						
	DIMM1		DIMM2		Margin At BER 10e-18	
	Rank1	Rank2	Rank3	Rank4	EH_Margin	EW_Margin
WR to Rank1	<u>240ohm</u>	60ohm	60ohm	60ohm	17mV	118ps
RD from Rank1	<u>50ohm (Ron)</u>	60ohm	60ohm	60ohm	35mV	83ps

ODT Matrix for 2DPC DQ Tee Topology Channel @ 2400MT/s						
	DIMM1		DIMM2		Margin At BER 10e-18	
	Rank1	Rank2	Rank3	Rank4	EH_Margin	EW_Margin
WR to Rank1	<u>240ohm</u>	60ohm	60ohm	60ohm	-5mV	76ps
RD from Rank1	<u>50ohm (Ron)</u>	60ohm	60ohm	60ohm	10mV	72ps

- Full channel eye diagram simulation was performed with 8 parallel DQ signals for WC crosstalk consideration at both 2133 MT/s and 2400 MT/s.
- The optimized channel passed the DDR4 specification [6] with a 17 mV/118 ps margin in write-mode EH/EW and a 35 mV/83 ps margin in read-mode EH/EW for 2133 MT/s speed, with a -5 mV/76 ps margin in write-mode EH/EW and a 10 mV/72 ps margin in read-mode EH/EW.

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Summary

- ✓ Presented the basic concept of the passive stub equalizer, which can be easily implemented on package or board level.
- ✓ Presented three design parameters to enable the passive stub equalizer.
- ✓ Demonstrated the performance of the passive stub equalizer through both simulation and measurement in frequency and time domain.
- ✓ Presented a design example for the adoption of the passive stub equalizer design concept to 1600 MT/s 4-ranks LPDDR3 command/address signal.
- ✓ Presented a design example for the adoption of the passive stub equalizer design concept to 2400 MT/s 4-ranks DDR4 DQ signal.



Q & A